- Member of the Texas Instruments Widebus™ Family

- Operates From 2.7 V to 3.6 V

- Inputs Accept Voltages to 5.5 V

- Max t_{pd} of 3.7 ns at 3.3 V

- I_{off} and Power-Up 3-State Support Hot Insertion

- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})

- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II

- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 1000-V Charged-Device Model (C101)

DGG, DGV, OR DL PACKAGE
(TOP VIEW)

1DIR	1	48	1$\overline{OE}$
1B1	2	47	1A1
1B2	3	46	1A2
GND	4	45	GND
1B3	5	44	1A3
1B4	6	43	1A4
V_{CC}	7	42	V_{CC}
1B5	8	41	1A5
1B6	9	40	1A6
GND	10	39	GND
1B7	11	38	1A7
1B8	12	37	1A8
2B1	13	36	2A1
2B2	14	35	2A2
GND	15	34	GND
2B3	16	33	2A3
2B4	17	32	2A4
V_{CC}	18	31	V_{CC}
2B5	19	30	2A5
2B6	20	29	2A6
GND	21	28	GND
2B7	22	27	2A7
2B8	23	26	2A8
2DIR	24	25	2$\overline{OE}$

description/ordering information

This 16-bit (dual-octal) noninverting bus transceiver is designed for 2.7-V to 3.6-V V_{CC} operation.
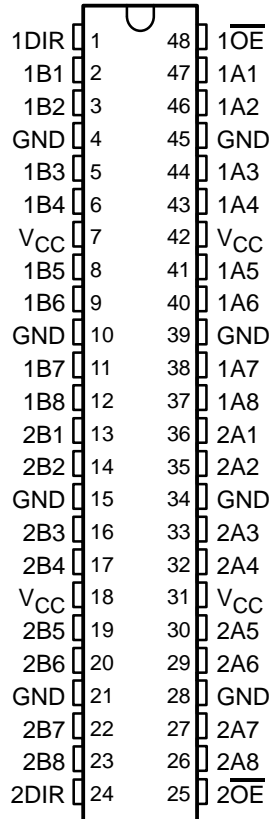
The SN74LVCZ16245A is designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so that the buses are effectively isolated.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SSOP – DL	Tube	SN74LVCZ16245ADL	LVCZ16245A
		Tape and reel	SN74LVCZ16245ADLR	
	TSSOP – DGG	Tape and reel	SN74LVCZ16245ADGGR	LVCZ16245A
	TVSOP – DGV	Tape and reel	SN74LVCZ16245ADGVR	CW245A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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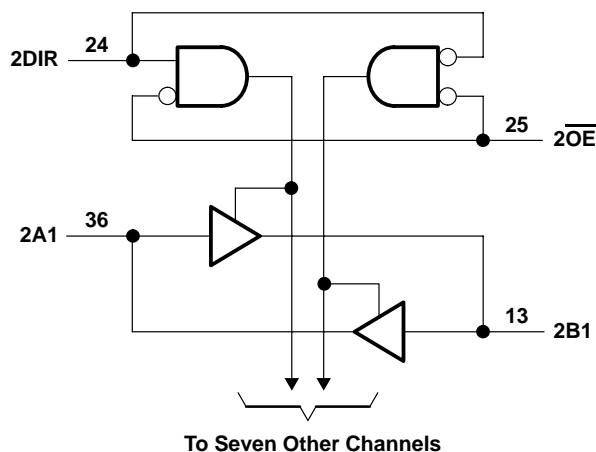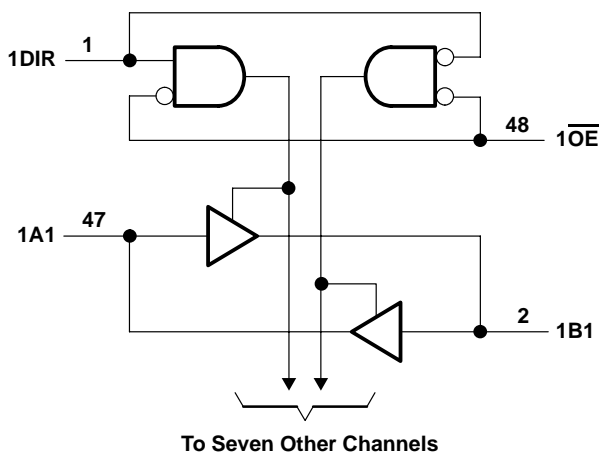
TEXAS INSTRUMENTS

description/ordering information (continued)

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic diagram (positive logic)

To Seven Other Channels

To Seven Other Channels

TEXAS
INSTRUMENTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . –0.5 V to 6.5 V

Input voltage range, V_I (see Note 1) . . . . –0.5 V to 6.5 V

Voltage range applied to any output in the high-impedance or power-off state, V_O
   (see Note 1) . . . . –0.5 V to 6.5 V

Voltage range applied to any output in the high or low state, V_O
   (see Notes 1 and 2) . . . . –0.5 V to V_{CC} + 0.5 V

Input clamp current, I_{IK} (V_I < 0) . . . . –50 mA

Output clamp current, I_{OK} (V_O < 0) . . . . –50 mA

Continuous output current, I_O . . . . ±50 mA

Continuous current through each V_{CC} or GND . . . . ±100 mA

Package thermal impedance, θ_{JA} (see Note 3): DGG package . . . . 70°C/W
                                        DGV package . . . . 58°C/W
                                        DL package . . . . 63°C/W

Storage temperature range, T_{stg} . . . . –65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
         2. The value of V_{CC} is provided in the recommended operating conditions table.
         3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2.7	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 2.7 V to 3.6 V	2		V
V_{IL}	Low-level input voltage	V_{CC} = 2.7 V to 3.6 V		0.8	V
V_I	Input voltage		0	5.5	V
V_O	Output voltage	High or low state	0	V_{CC}	V
		3-state	0	5.5	
I_{OH}	High-level output current	V_{CC} = 2.7 V		–12	mA
		V_{CC} = 3 V		–24	
I_{OL}	Low-level output current	V_{CC} = 2.7 V		12	mA
		V_{CC} = 3 V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			6	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		150		µs/V
T_A	Operating free-air temperature		–40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V_{CC}	MIN	TYP†	MAX	UNIT
V_{OH}		$I_{OH} = -100$ μA		2.7 V to 3.6 V	V_{CC}–0.2			V
		$I_{OH} = -12$ mA		2.7 V	2.2			
				3 V	2.4			
		$I_{OH} = -24$ mA		3 V	2.2			
V_{OL}		$I_{OL} = 100$ μA		2.7 V to 3.6 V			0.2	V
		$I_{OL} = 12$ mA		2.7 V			0.4	
		$I_{OL} = 24$ mA		3 V			0.55	
I_I	Control inputs	V_I = 0 to 5.5 V		3.6 V			±5	μA
I_{off}		V_I or V_O = 5.5 V		0			±5	μA
I_{OZ}‡		V_O = 0 to 5.5 V		3.6 V			±5	μA
I_{OZPU}		V_O = 0.5 V to 2.5 V,	$\overline{OE}$ = don't care	0 to 1.5 V			±5	μA
I_{OZPD}		V_O = 0.5 V to 2.5 V,	$\overline{OE}$ = don't care	1.5 V to 0			±5	μA
I_{CC}		V_I = V_{CC} or GND	I_O = 0	3.6 V			60	μA
		3.6 V ≤ V_I ≤ 5.5 V§					60	
ΔI_{CC}		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND		2.7 V to 3.6 V			500	μA
C_i	Control inputs	V_I = V_{CC} or GND		3.3 V		5		pF
C_{io}	A or B ports	V_O = V_{CC} or GND		3.3 V		6.5		pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.
§ This applies in the disabled state only.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}	A or B	B or A		4.2	1.3	4	ns
t_{en}	$\overline{OE}$	A or B		6.1	1.4	5.6	ns
t_{dis}	$\overline{OE}$	A or B		7.1	2	6.6	ns

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}	A or B	B or A		3.9	1	3.7	ns
t_{en}	$\overline{OE}$	A or B		5.9	1.1	5.4	ns
t_{dis}	$\overline{OE}$	A or B		6.7	1.6	6.2	ns

operating characteristics, $T_A = 25°C$

PARAMETER		TEST CONDITIONS	V_{CC} = 3.3 V TYP	UNIT
C_{pd} Power dissipation capacitance per transceiver	Outputs enabled	f = 10 MHz	42	pF
	Outputs disabled		4	

PARAMETER MEASUREMENT INFORMATION
V_{CC} = 2.7 V AND 3.3 V $\pm$ 0.3 V
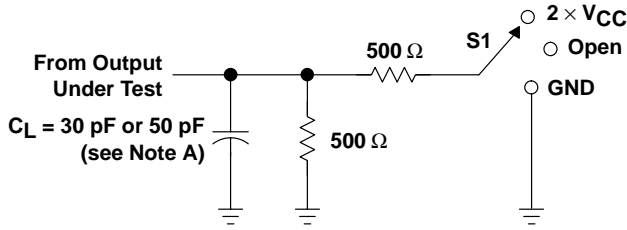
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

LOAD CIRCUIT
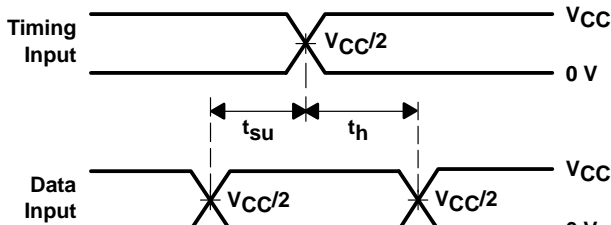
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PULSE DURATION
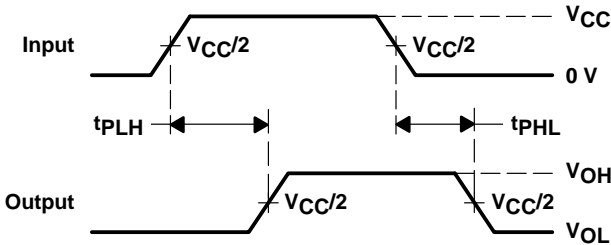
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
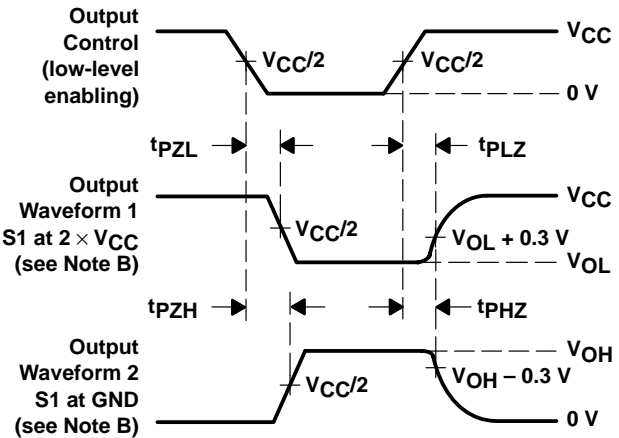
VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and jig capacitance.
  B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
     Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  C. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 10 MHz, Z_O = 50 Ω, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
  D. The outputs are measured one at a time with one transition per measurement.
  E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
  F. t_{PZL} and t_{PZH} are the same as t_{en}.
  G. t_{PLH} and t_{PHL} are the same as t_{pd}.
  H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
74LVCZ16245ADGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVCZ16245ADGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCZ16245ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCZ16245ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCZ16245ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVCZ16245ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGV (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

0,40

0,23
0,13   ⊕   0,07   Ⓜ

24   13

4,50   6,60
4,30   6,20

1   12

A

0,16 NOM

Gage Plane

0,25

0°−8°

0,75
0,50

1,20 MAX

0,15
0,05

Seating Plane

⌒ 0,08

DIM \\ PINS **	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

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DL (R-PDSO-G)**   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

0.025 (0,635)

$\dfrac{0.0135\ (0,343)}{0.008\ (0,203)}$

⊕ 0.005 (0,13) Ⓜ

48   25

$\dfrac{0.299\ (7,59)}{0.291\ (7,39)}$

$\dfrac{0.420\ (10,67)}{0.395\ (10,03)}$

$\dfrac{0.010\ (0,25)}{0.005\ (0,13)}$

Gage Plane

0.010 (0,25)

0°–8°

$\dfrac{0.040\ (1,02)}{0.020\ (0,51)}$

1   24

A

0.110 (2,79) MAX   0.008 (0,20) MIN

Seating Plane

△ 0.004 (0,10)

PINS ** DIM	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048/E 12/01

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MO-118

DGG (R-PDSO-G**) PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

	PINS **	48	56	64
DIM				
A MAX		12,60	14,10	17,10
A MIN		12,40	13,90	16,90

4040078 / F 12/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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